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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings		Unit
		MOS1	MOS2 & SBD	
Drain to source voltage	V_{DSS}	30	30	V
Gate to source voltage	V_{GSS}	±20	±12	V
Drain current	I_D	12	16	A
Drain peak current	$I_{D(pulse)}$ ^{Note1}	96	128	A
Reverse drain current	I_{DR}	12	16	A
Channel dissipation	Pch ^{Note2}	2.0	3.5	W
Channel temperature	Tch	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

Notes: 1. $PW \leq 10\mu s$, duty cycle $\leq 1\%$

2. 1 Drive operation; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), $PW \leq 10s$

Electrical Characteristics

(Ta = 25°C)

• MOS1

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10\text{mA}$, $V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	± 20	—	—	V	$I_G = \pm 100\mu\text{A}$, $V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 16\text{V}$, $V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1	μA	$V_{DS} = 30\text{V}$, $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.5	V	$V_{DS} = 10\text{V}$, $I_D = 1\text{mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	10	13	m Ω	$I_D = 6\text{A}$, $V_{GS} = 10\text{V}$ ^{Note3}
	$R_{DS(on)}$	—	18	27	m Ω	$I_D = 6\text{A}$, $V_{GS} = 4.5\text{V}$ ^{Note3}
Forward transfer admittance	$ y_{fs} $	12	20	—	S	$I_D = 6\text{A}$, $V_{DS} = 10\text{V}$ ^{Note3}
Input capacitance	Ciss	—	1000	—	pF	$V_{DS} = 10\text{V}$
Output capacitance	Coss	—	280	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	160	—	pF	$f = 1\text{MHz}$
Total gate charge	Qg	—	9	—	nc	$V_{DD} = 10\text{V}$
Gate to source charge	Qgs	—	3.6	—	nc	$V_{GS} = 5\text{V}$
Gate to drain charge	Qgd	—	3.2	—	nc	$I_D = 16\text{A}$
Turn-on delay time	$t_{d(on)}$	—	12	—	ns	$V_{GS} = 10\text{V}$, $I_D = 6\text{A}$
Rise time	t_r	—	22	—	ns	$V_{DD} \approx 10\text{V}$
Turn-off delay time	$t_{d(off)}$	—	55	—	ns	$R_L = 1.67\Omega$
Fall time	t_f	—	9	—	ns	$R_g = 4.7\Omega$
Body-drain diode forward voltage	V_{DF}	—	0.82	1.07	V	$I_F = 12\text{A}$, $V_{GS} = 0$ ^{Note3}
Body-drain diode reverse recovery time	t_{rr}	—	25	—	ns	$I_F = 12\text{A}$, $V_{GS} = 0$ $diF/dt = 50\text{A}/\mu\text{s}$

Notes: 3. Pulse test

HAT2126RP

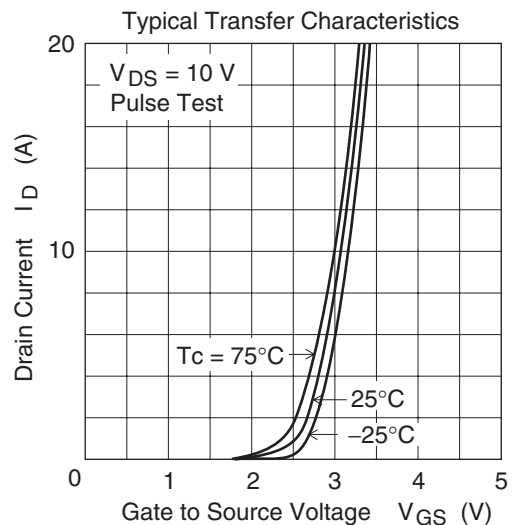
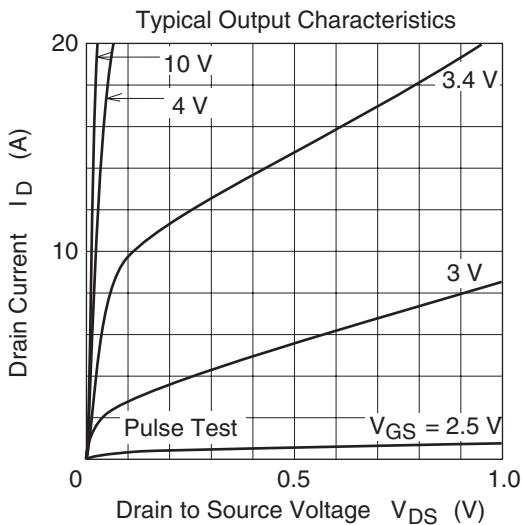
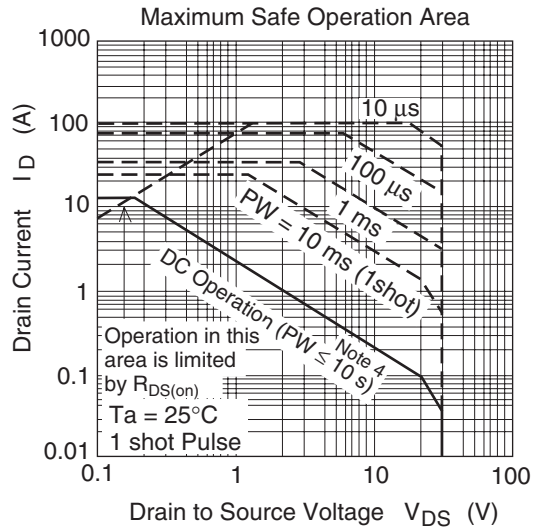
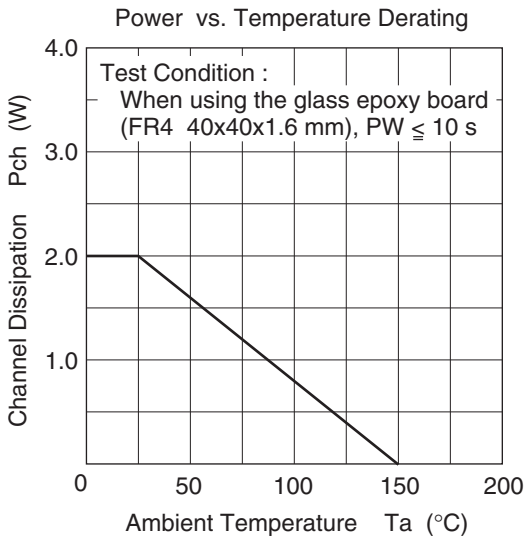
• MOS2 & Schottky Barrier Diode

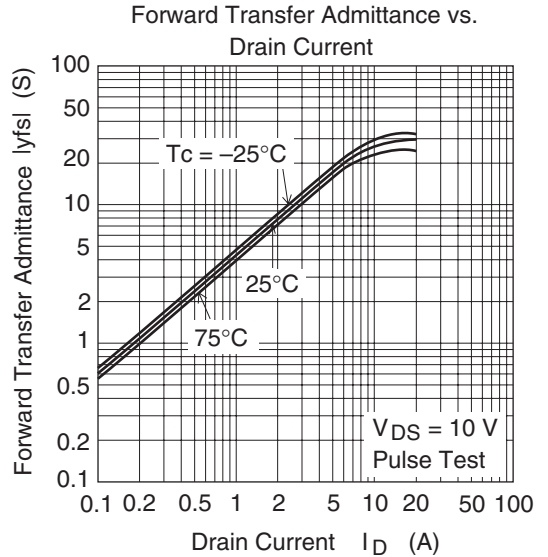
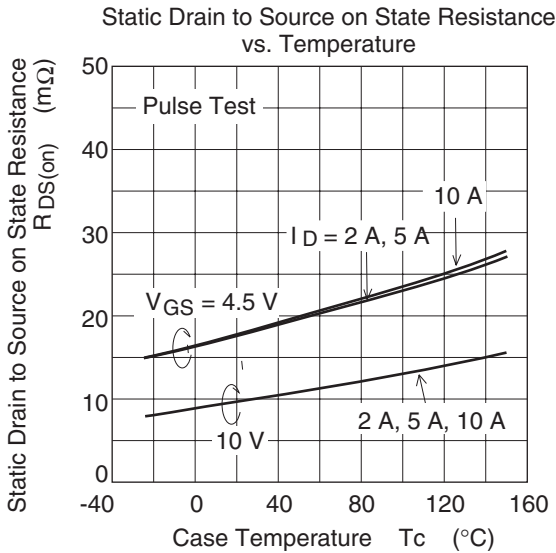
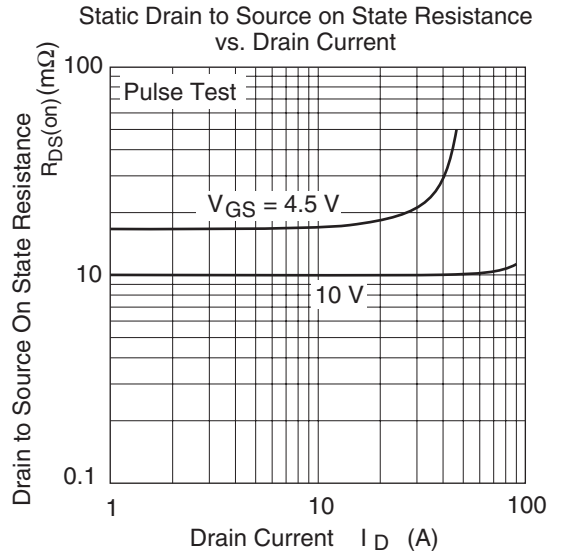
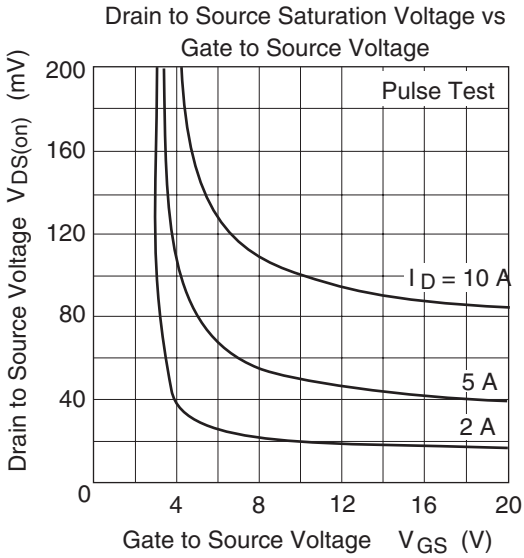
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10\text{mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	± 12	—	—	V	$I_G = \pm 100\mu\text{A}, V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 10\text{V}, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1	m A	$V_{DS} = 30\text{V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.4	—	2.5	V	$V_{DS} = 10\text{V}, I_D = 1\text{mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	5.6	7.3	$\text{m}\Omega$	$I_D = 8\text{A}, V_{GS} = 10\text{V}$ ^{Note3}
	$R_{DS(on)}$	—	7.3	9.5	$\text{m}\Omega$	$I_D = 8\text{A}, V_{GS} = 4.5\text{V}$ ^{Note3}
Forward transfer admittance	$ y_{fs} $	25	41	—	S	$I_D = 8\text{A}, V_{DS} = 10\text{V}$ ^{Note3}
Input capacitance	Ciss	—	3800	—	pF	$V_{DS} = 10\text{V}$
Output capacitance	Coss	—	745	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	300	—	pF	$f = 1\text{MHz}$
Total gate charge	Qg	—	34	—	nc	$V_{DD} = 10\text{V}$
Gate to source charge	Qgs	—	10	—	nc	$V_{GS} = 5\text{V}$
Gate to drain charge	Qgd	—	8	—	nc	$I_D = 16\text{A}$
Turn-on delay time	$t_{d(on)}$	—	18	—	ns	$V_{GS} = 10\text{V}, I_D = 8\text{A}$
Rise time	t_r	—	22	—	ns	$V_{DD} \approx 10\text{V}$
Turn-off delay time	$t_{d(off)}$	—	88	—	ns	$R_L = 1.25\Omega$
Fall time	t_f	—	9.0	—	ns	$R_g = 4.7\Omega$
Schottky Barrier diode forward voltage	V_F	—	0.5	—	V	$I_F = 3.5\text{A}, V_{GS} = 0$ ^{Note3}
Body-drain diode reverse recovery time	t_{rr}	—	35	—	ns	$I_F = 16\text{A}, V_{GS} = 0$ $diF/dt = 50\text{A}/\mu\text{s}$

Notes: 3. Pulse test

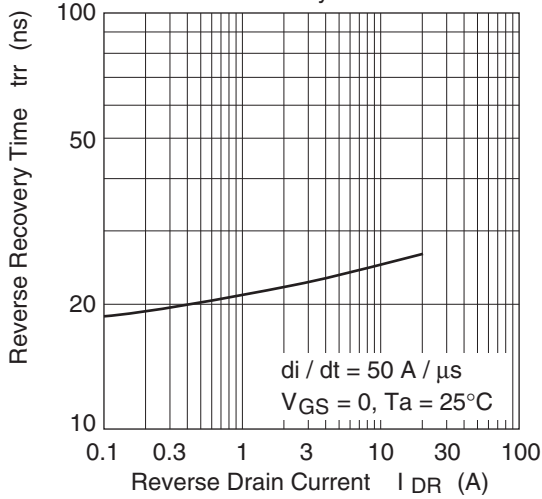
Main Characteristics

• MOS1

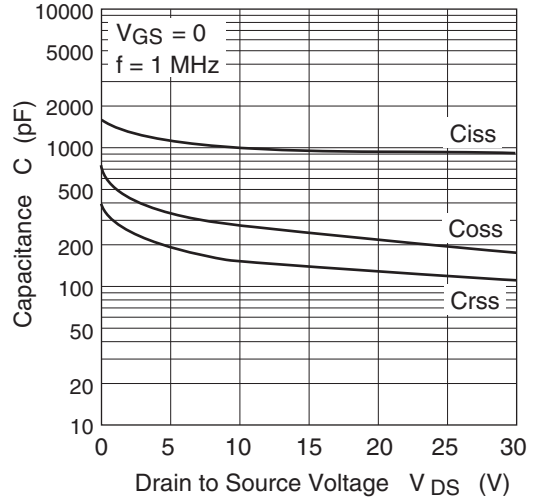




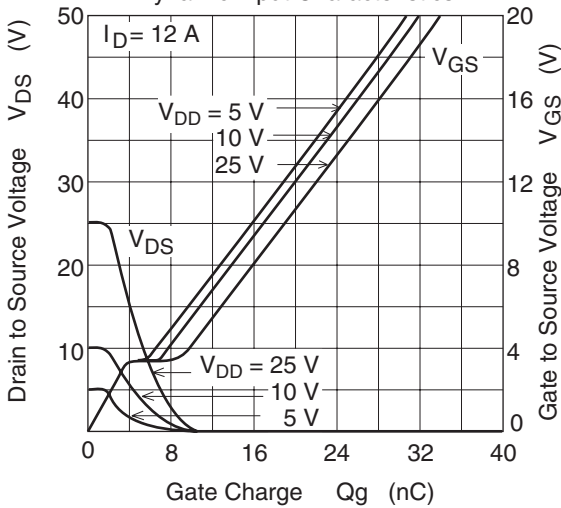
Body-Drain Diode Reverse Recovery Time



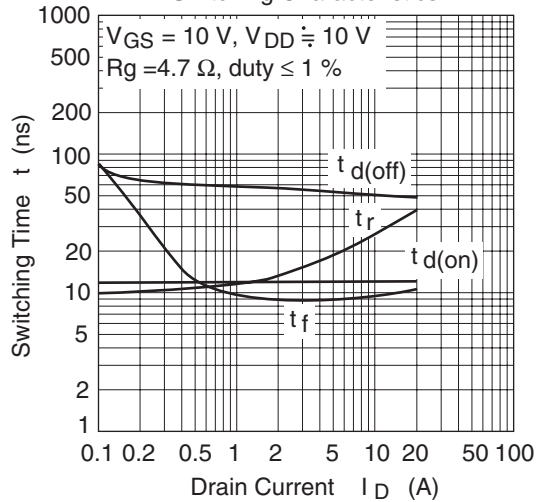
Typical Capacitance vs. Drain to Source Voltage

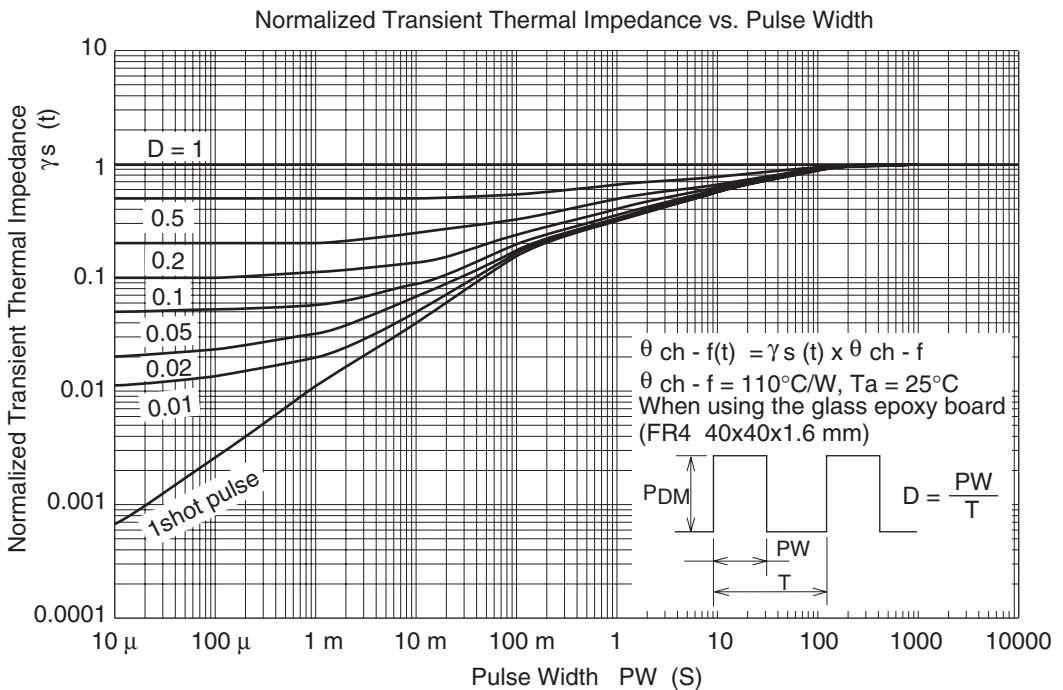
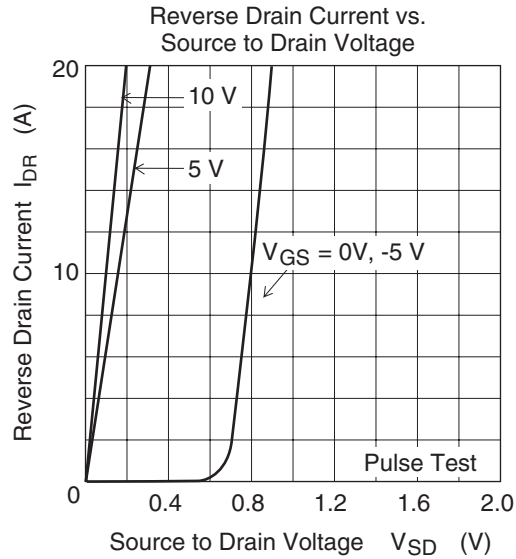


Dynamic Input Characteristics

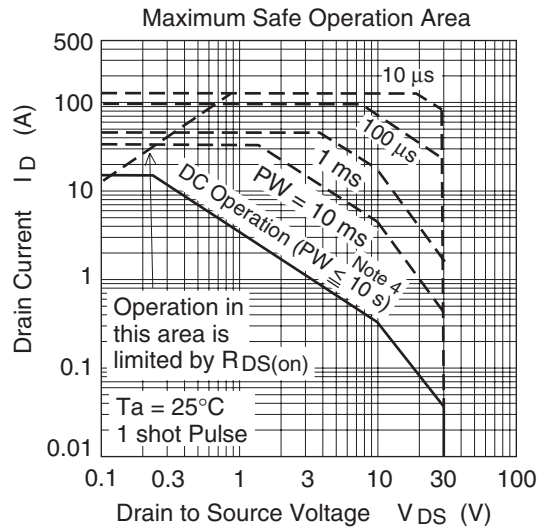
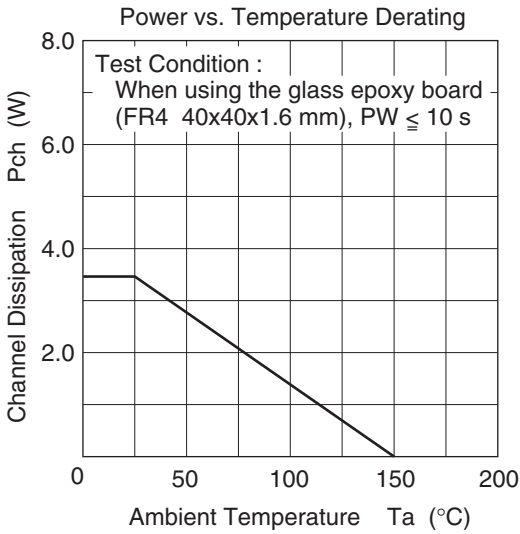


Switching Characteristics

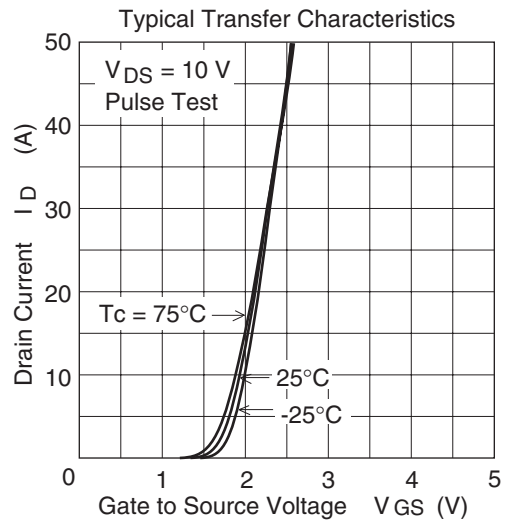
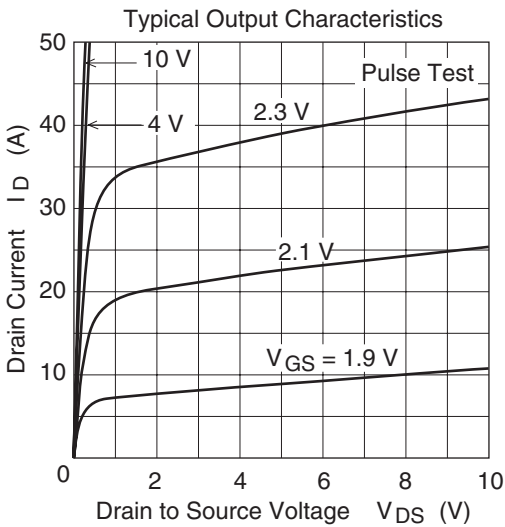




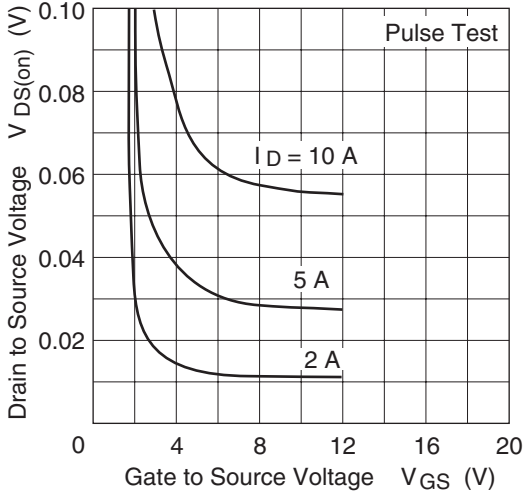
• MOS2 & Schottky Barrier Diode



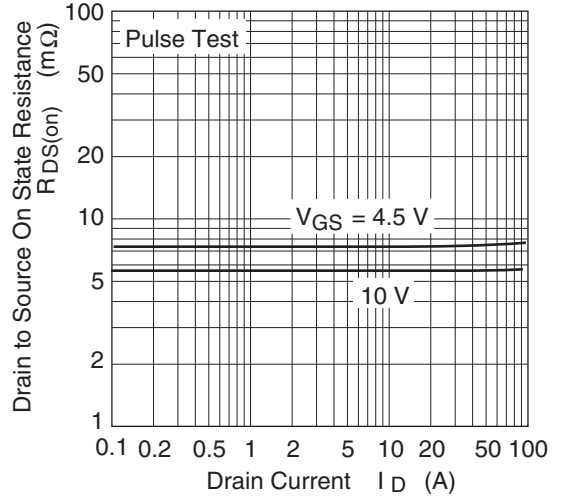
Note 4 :
When using the glass epoxy board (FR4 40x40x1.6 mm)



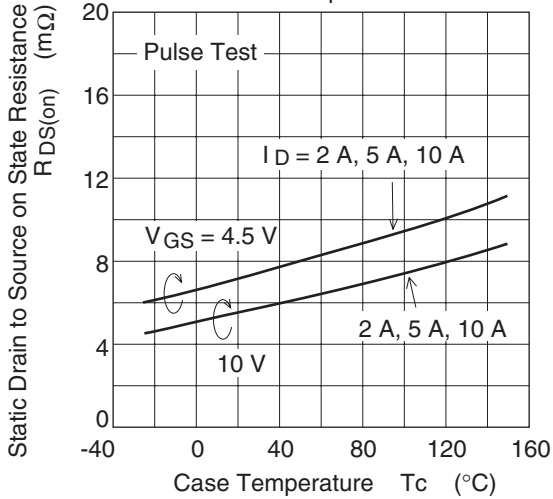
Drain to Source Saturation Voltage vs. Gate to Source Voltage



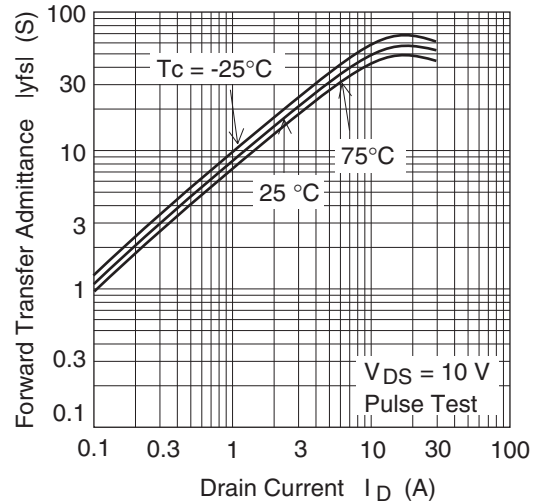
Static Drain to Source on State Resistance vs. Drain Current



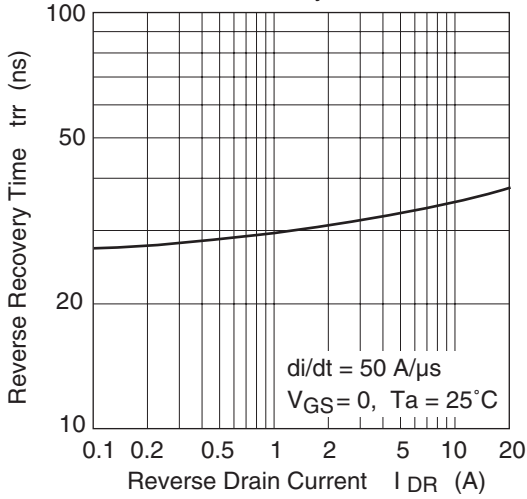
Static Drain to Source on State Resistance vs. Temperature



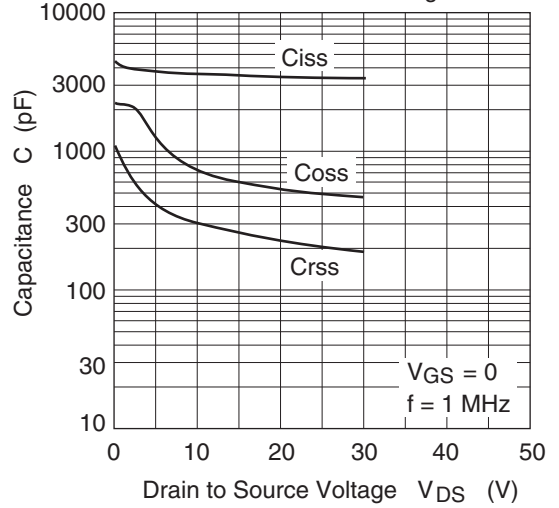
Forward Transfer Admittance vs. Drain Current



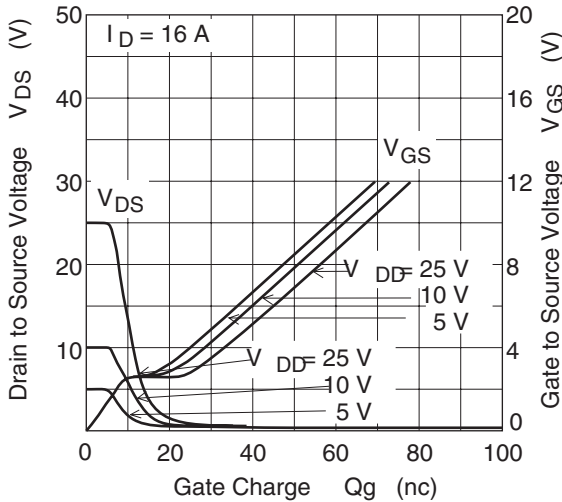
Body - Drain Diode Reverse Recovery Time



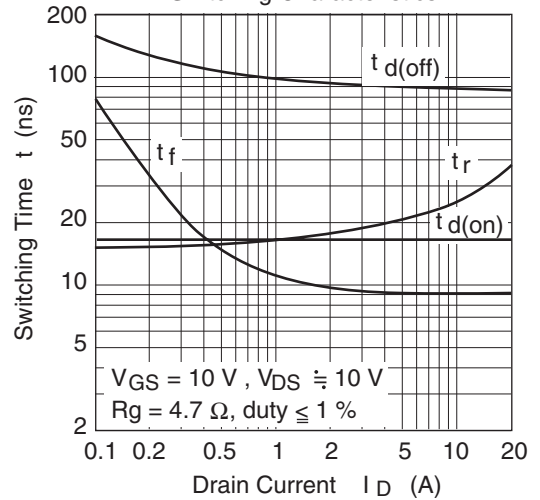
Typical Capacitance vs. Drain to Source Voltage

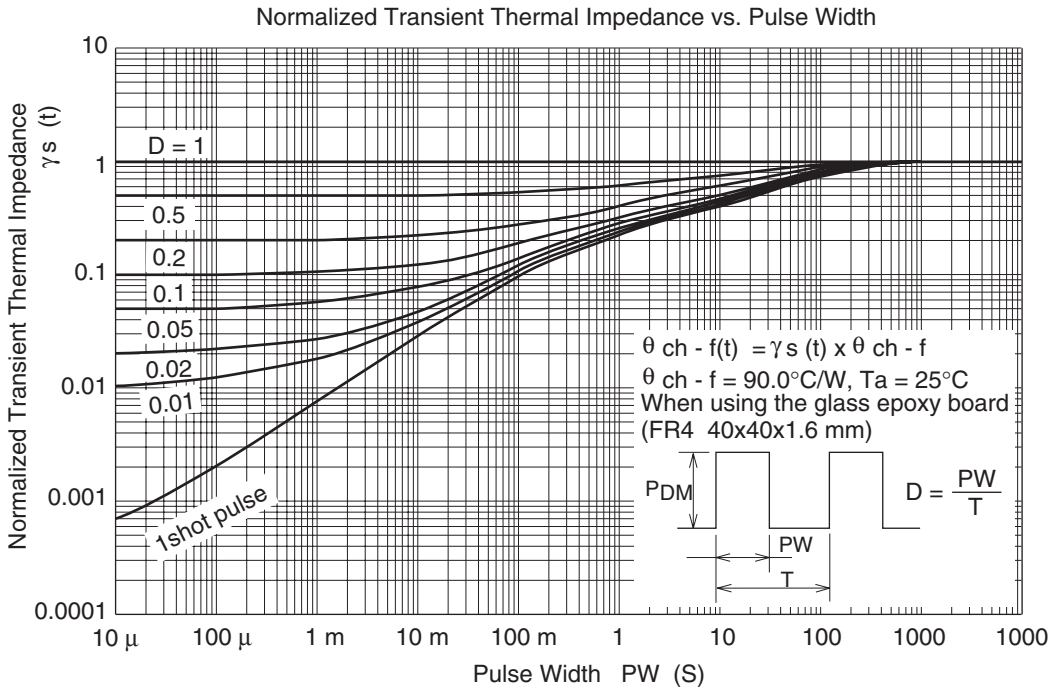
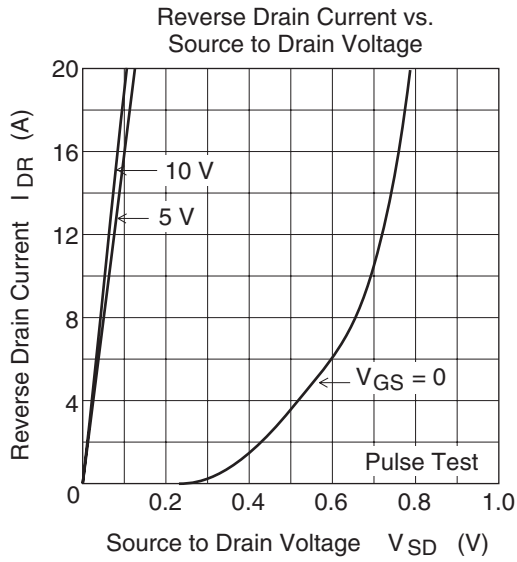


Dynamic Input Characteristics

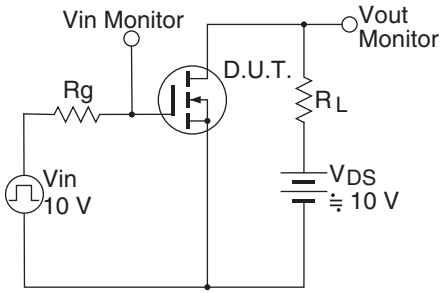


Switching Characteristics

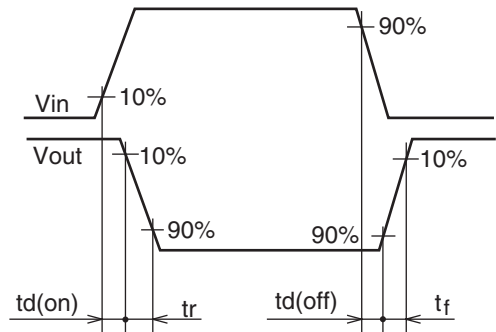




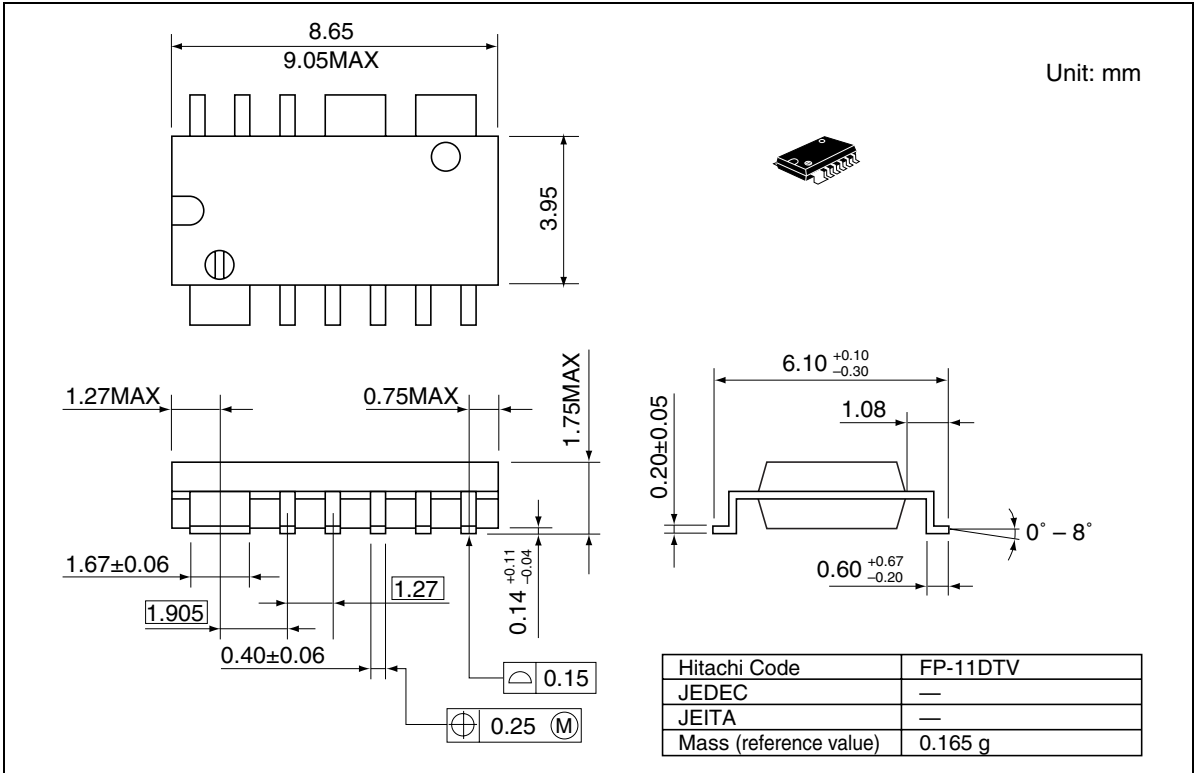
Switching Time Test Circuit



Switching Time Waveform



Package Dimensions



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